



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
LATCHS: THERMOPLASTIC WITHOUT GLASS FIBER, UL94-HB (PA66).
CONTACTS: COPPER ALLOY.

2.FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u" MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER
BY 25 DEGREE.

4. DURABILITY: 50 CYCLES.

5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 1.5um min. MATTE PURE TIN OVER 1.27um MIN.
NICKEL UNDERPLATE.
- b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C $\pm$ 5C^o
SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH
A 1.57MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10083987 -x x x x x x LF

HOUSING COLOR OPTIONS

- 1-BLACK FOR BASE & RM
4-BLUE (297C) FOR BASE & RM

APPLICATIONS

LF- LEAD FREE FOR PLATING OPTIONS 0,1,2

PACKAGING OPTIONS

T-TRAY PACKAGING

PEGS OPTIONS

1-PLASTIC POST

POS OPTIONS

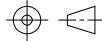
3-164

TERMINAL PLATING OPTIONS

- 0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA
1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA
2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA

TAIL LENGTH OPTION (DIM.A)

- 1- 3.10MM
2- 2.30MM

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X $\pm$ 0.38 .XX $\pm$ 0.25 .XXX $\pm$ 0.10 angles 0 $^{\circ}$ $\pm$ 2 $^{\circ}$		projection	title		
								PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y 		
				dr	STONE LI 05/27/15		MM	product family	EDGE CARD	code
				enrg	STONF LI 05/27/15			size	dwg no	TWN
				chr	/		scale	A4		sheet
				appd	PM ZHENG 05/27/15		1:1	10083987		3 of
sheet index	revision sheet									

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